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Vishay Semiconductors

RoHS

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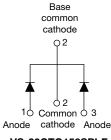
HALOGEN

FREE

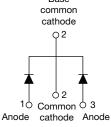
High Performance Schottky Rectifier, 2 x 10 A

TO-263AB (D²PAK)









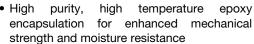
VS-20CTQ150-1PbF

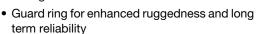
VS-20CTQ150SPbF

PRODUCT SUMMARY	PRODUCT SUMMARY					
I _{F(AV)}	2 x 10 A					
V _R	150 V					
V _F at I _F	0.66 V					
I _{RM} max.	5.0 mA at 125 °C					
T _J max.	175 °C					
E _{AS}	1.0 mJ					
Package	TO-263AB (D ² PAK), TO-262AA					
Diode variation	Common cathode					

FEATURES

- 175 °C T_J operation
- · Center tap configuration
- · Low forward voltage drop
- · High frequency operation





- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION

This center tap Schottky rectifier has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL	CHARACTERISTICS	VALUES	UNITS			
I _{F(AV)}	Rectangular waveform	20	А			
V _{RRM}		150	V			
I _{FSM}	t _p = 5 μs sine	1030	А			
V _F	10 A _{pk} , T _J = 125 °C (per leg)	0.66	V			
TJ	Range	-55 to +175	°C			

VOLTAGE RATINGS					
PARAMETER SYMBOL VS-20CTQ150SPbF VS-20CTQ150-1PbF UNITS					
Maximum DC reverse voltage	V_{R}	150	V		
Maximum working peak reverse voltage	V_{RWM}	130	V		

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward per leg		50.0/		10	
See fig. 5 per device	I _{F(AV)}	50 % duty cycle at T_C = 154 °C, rectangular waveform		20	
Maximum peak one cycle	peak one cycle 5 µs sine or 3 µs rect.		Following any rated load condition and with	1030	А
non-repetitive surge current per leg See fig. 7	IFSM	10 ms sine or 6 ms rect. pulse	rated V _{RRM} applied	180	
Non-repetitive avalanche energy per leg	E _{AS}	$T_J = 25 ^{\circ}\text{C}$, $I_{AS} = 1 \text{A}$, $L = 2 \text{mH}$		1.0	mJ
Repetitive avalanche current per leg	I _{AR}	Current decaying linearly to zer Frequency limited by T _J maxim		ed V _{RRM} applied 180 1.0 mJ	



VS-20CTQ150SPbF, VS-20CTQ150-1PbF

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ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CO	NDITIONS	TYP.	MAX.	UNITS
		10 A	T _{.1} = 25 °C	0.80	0.88	
Maximum forward voltage drop per leg See fig. 1	V _{FM} ⁽¹⁾	20 A	1j=25 C	0.90	1.0	V
		10 A	T _J = 125 °C	0.63	0.66	
		20 A		0.73	0.77	
Maximum reverse leakage current per leg	I _{RM} ⁽¹⁾	T _J = 25 °C	V _R = Rated V _R	3.0	25	μΑ
See fig. 2	'RM '''	T _J = 125 °C	v _R = nated v _R	2.7	5.0	mA
Typical junction capacitance per leg	C _T	V _R = 5 V _{DC} (test signal rang	ge 100 kHz to 1 MHz), 25 °C	-	280	pF
Typical series inductance per leg	L _S	Measured lead to lead 5 m	m from package body	-	8.0	nH
Maximum voltage rate of change	dV/dt	Rated V _R		-	10 000	V/µs

Note

 $^{^{(1)}\,}$ Pulse width $<300~\mu s,$ duty cycle <2~%

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range		T _J , T _{Stg}		-55 to +175	°C
Maximum thermal resistance,	per leg	D	DC operation	2.0	
junction to case	per package	R _{thJC} DC operation	1.0	°C/W	
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased (Only for TO-262)	0.50	3, 11
Approximate weight				2	g
Approximate weight				0.07	OZ.
Mounting torque	minimum			6 (5)	kgf · cm
Mounting torque	maximum			12 (10)	(lbf·in)
Mayking daying	Madding de to		Case style D ² PAK	20CTC	150S
Marking device			Case style TO-262	20CTC	150-1



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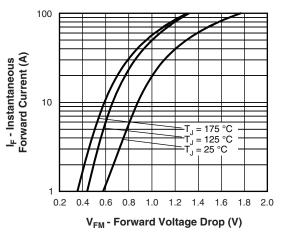


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

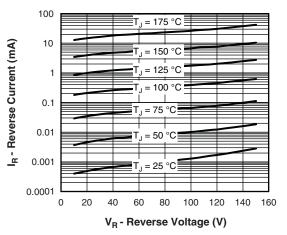


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

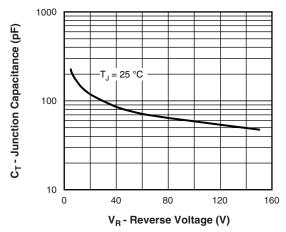


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

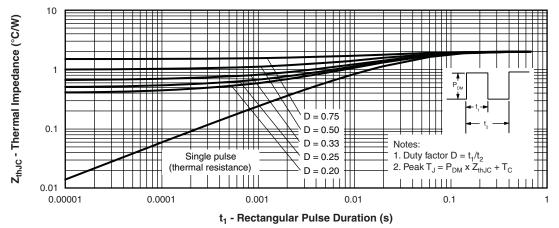


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



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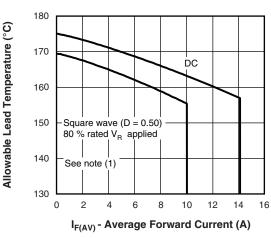
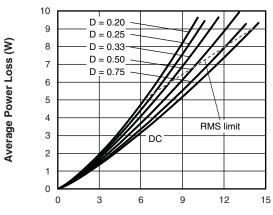


Fig. 5 - Maximum Average Forward Current vs. Allowable Lead Temperature



I_{F(AV)} - Average Forward Current (A)

Fig. 6 - Maximum Average Forward Dissipation vs.

Average Forward Current

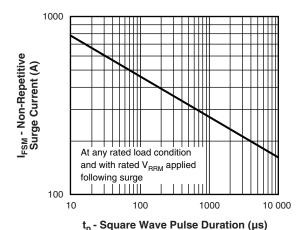


Fig. 7 - Maximum Peak Surge Forward Current vs. Pulse Duration

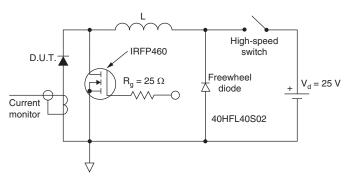


Fig. 8 - Unclamped Inductive Test Circuit

Note

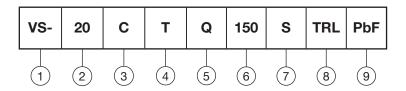
 $\begin{array}{l} \text{(1)} \ \ \text{Formula used:} \ T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \ \text{at} \ (I_{F(AV)}/D) \ \text{(see fig. 6)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \ \text{(1 - D)}; \ I_R \ \text{at} \ V_{R1} = 80 \ \% \ \text{rated} \ V_R \\ \end{array}$

VS-20CTQ150SPbF, VS-20CTQ150-1PbF

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (20 = 20 A)

3 - C = common cathode

4 - T = TO-220

5 - Schottky "Q" series

6 - Voltage rating (150 = 150 V)

7 - • S = D²PAK

• -1 = TO-262

None = tube

• TRL = tape and reel (left oriented - for D²PAK only)

• TRR = tape and reel (right oriented - for D²PAK only)

9 - PbF = lead (Pb)-free

ORDERING INFORMATION (Example)					
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION		
VS-20CTQ150SPbF	50	1000	Antistatic plastic tubes		
VS-20CTQ150STRLPbF	800	800	13" diameter reel		
VS-20CTQ150STRRPbF	800	800	13" diameter reel		
VS-20CTQ150-1PbF	50	1000	Antistatic plastic tubes		

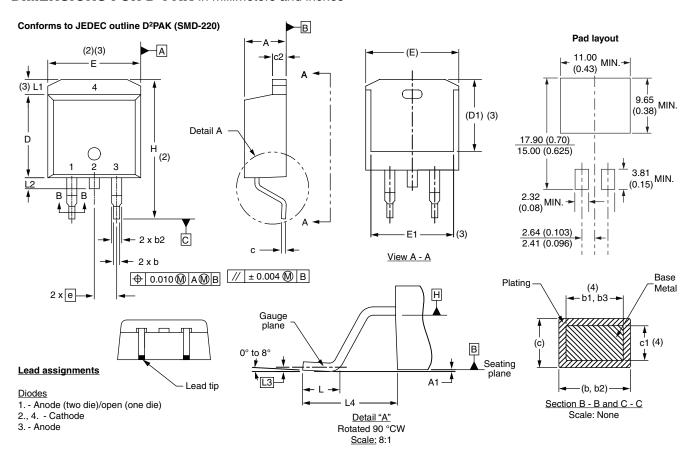
LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95014</u>				
Part marking information	www.vishay.com/doc?95008			
Packaging information	www.vishay.com/doc?95032			



Vishay High Power Products

D²PAK, TO-262

DIMENSIONS FOR D²PAK in millimeters and inches



CVMDOL	MILLIM	IETERS	INC	NOTEO	
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- $^{(3)}\,$ Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

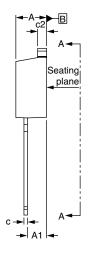
(7) Outline conforms to JEDEC outline TO-263AB

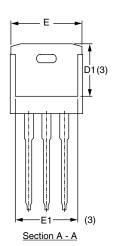
Vishay High Power Products

D²PAK, TO-262



DIMENSIONS FOR TO-262 in millimeters and inches





⊕ 0.010**⋒**|A**⋒**|B

Lead assignments

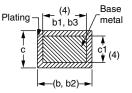


<u>Diodes</u>

-3 x b2 --3 x b

> 1. - Anode (two die)/open (one die) 2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

OVMDOL	MILLIMETERS		INC	CHES	NOTES	
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2 1.14	c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
E	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54 BSC		0.10	0 BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.56	3.71	0.140	0.146		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches

(6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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